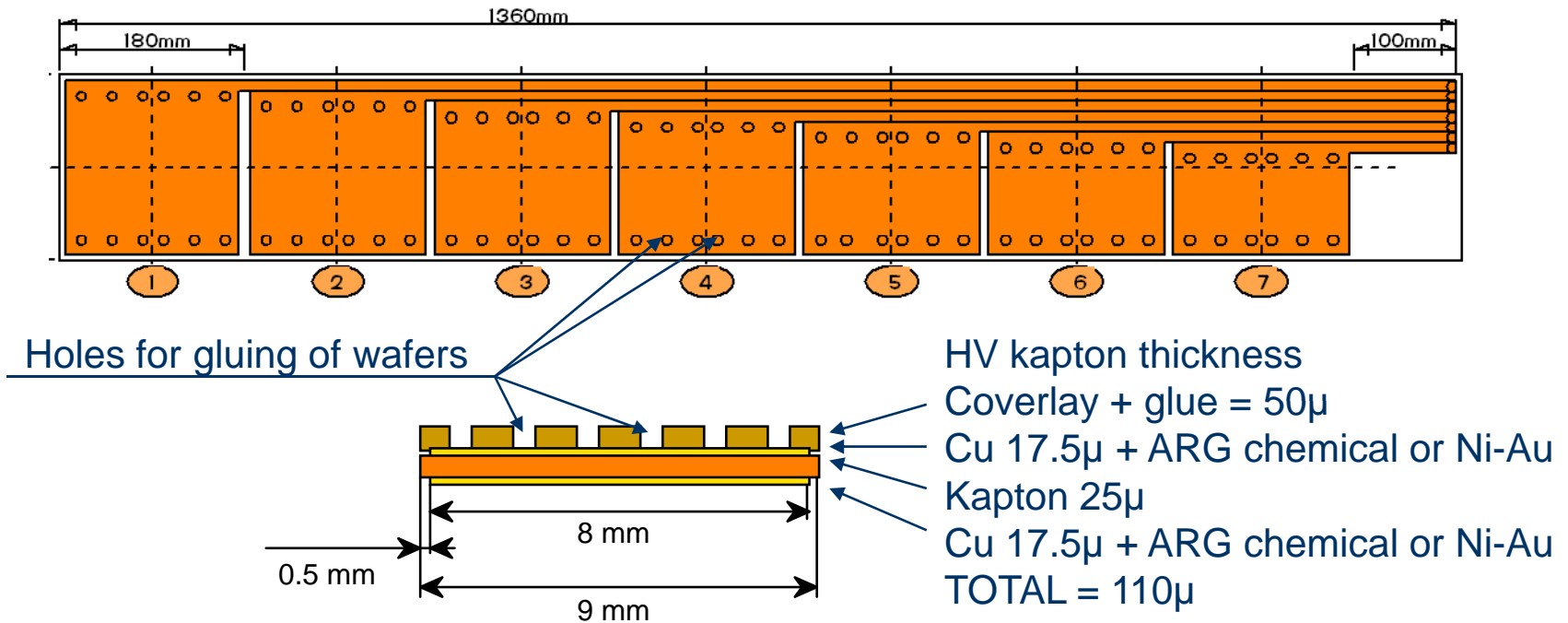




EUDET HV Kapton and Demonstrator Thermal PCB

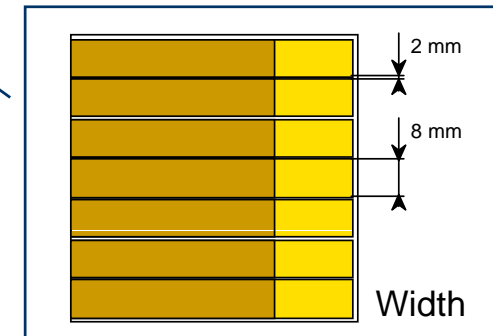
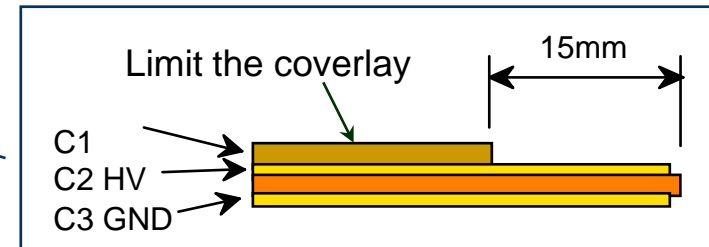
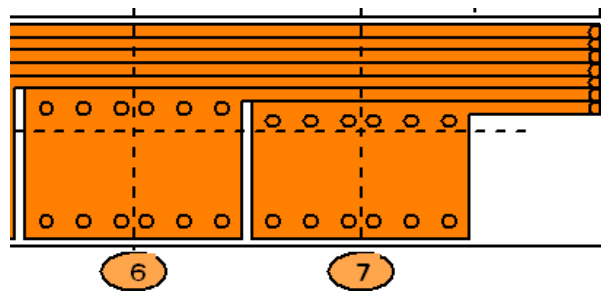
HV KAPTON

- One single HV kapton with 7 area for PCB with wafers

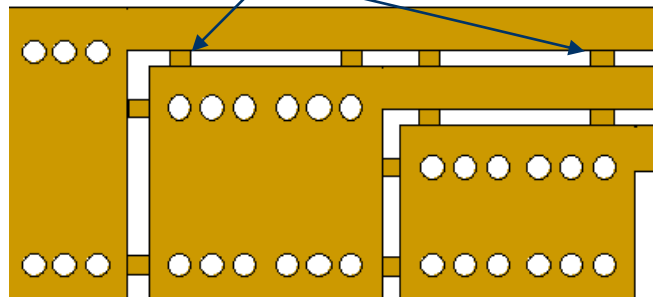


HV KAPTON

HV connection and ground connection to adapted card or diff card to be defined



Option to isolate an area if PCB exhibits problems with cutting strips





HV KAPTON

- Large exploration to find a manufacturer and the choice for production is CERN
- The Kapton drawing from LAL CAO J.L Socha was sent last week to CERN
- Delivery of Kapton is scheduled for late january
- Manufacturing in february

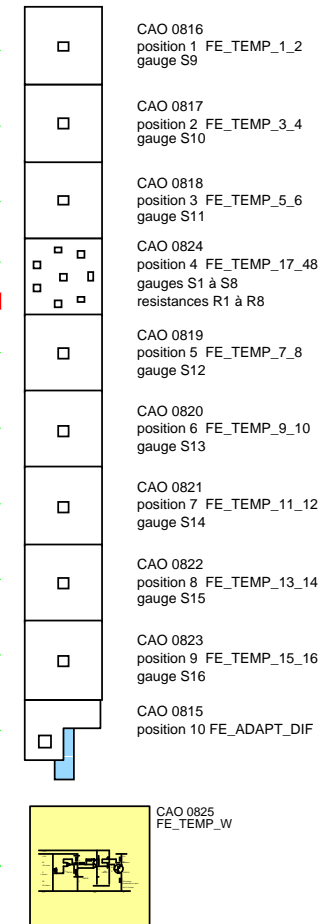


THERMAL PCB

PCBs delivery by manufacture

- 1: 2/2 FE_TEMP_1_2 CAO 0816 at Manchester
 - 2: 2/2 FE_TEMP_3_4 CAO 0817 at Manchester
 - 3: 2/2 FE_TEMP_5_6 CAO 0818 at Manchester
 - 4: 1/4 FE_TEMP_17_48 CAO 0824 at Manchester
 - 5: 2/2 FE_TEMP_7_8 CAO 0819 at Manchester
 - 6: 2/2 FE_TEMP_9_10 CAO 0820 at Manchester
 - 7: 2/2 FE_TEMP_11_12 CAO 0821 at Manchester
 - 8: 2/2 FE_TEMP_13_14 CAO 0822 at Manchester
 - 9: 2/2 FE_TEMP_15_16 CAO 0823 at Manchester
 - 10: 4/4 FE_ADAPT_DIFF CAO 0815 at cabling
 - 11: 3/3 FE_TEMP_W CAO 0825 waiting components
- PCBs Pending**
- 4: 3/4 FE_TEMP_17_48 CAO 0824 expected week 50

●Send last cards to Manchester end of december or beginning of january

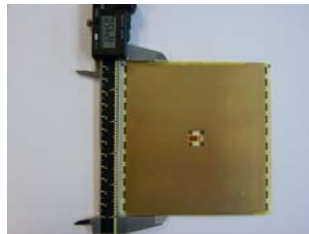




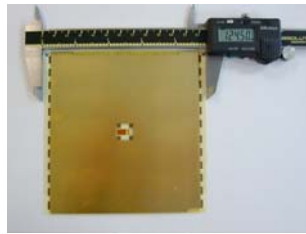
THERMAL PCB

PCB FEV_TEMP

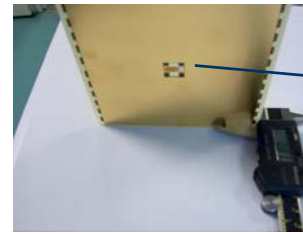
Width expected 124.5 mm
Width made 124.5 mm



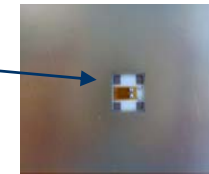
Length expected 124.5 mm
Length made 124.5 mm



Thickness expected 0.8 mm
Thickness made 0.81 mm



The gauge is now glued and cabling inside the PCB



PCB FEV_ADAPT_DIFF

Width 95 mm



Thickness 0.9 mm



PCB FEV_HEATERS

